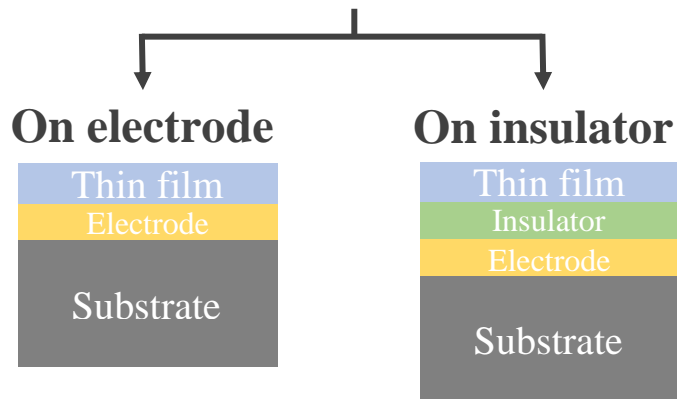


## Thin films on hybrid wafers



Specifications	
Wafer size	3 or 4 inch
Thin film materials	LiNbO <sub>3</sub> , LiTaO <sub>3</sub> , Quartz, PZT, LGT, glass and other materials on request
Substrate materials	Sapphire, Si, LiNbO <sub>3</sub> , LiTaO <sub>3</sub> , Quartz, PZT, LGT, glass and other materials on request
Thin film thickness	1 μm ~ 100 μm
Thin film TTV (Total Thickness Variation)	< 1 μm

These thin films on hybrid wafers (patented process) can be advantageously used for Radio Frequency, photonic and MEMS applications. They allow to explore news devices and to improve their performances (as the sensitivity, efficiency, miniaturization, integration). These hybrid wafers are suitable for microfabrication technologies like photolithography, etching, dicing and deposition processes.

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